PCN Number:	20180411001.1	PCN Date:	Apr 16, 2018
Title:	Qualification of RFAB for select devices in the LBC8LV process technology		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jul 16, 2018	Estimated Sample Availability:	Date provided at sample request.

Change Type:		
☐ Assembly Site	☐ Assembly Process	☐ Assembly Materials
☐ Design	☐ Electrical Specification	☐ Mechanical Specification
☐ Test Site	☐ Packing/Shipping/Labeling	☐ Test Process
☐ Wafer Bump Site	☐ Wafer Bump Material	☐ Wafer Bump Process
☒ Wafer Fab Site	☒ Wafer Fab Materials	☐ Wafer Fab Process
	☐ Part number change	

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional wafer fab site option for the LBC8LV devices listed in the product affected section of this document.

Current Sites			Additional Sites		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
DP1DM5	LBC8LV	200 mm	RFAB	LBC8LV	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

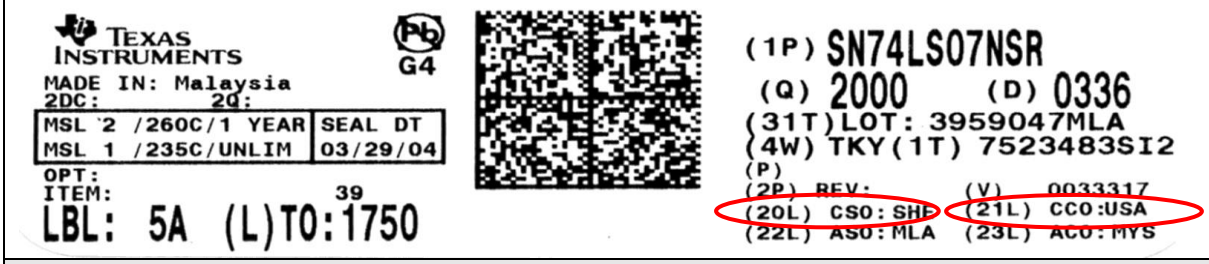
Current:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label)



Product Affected:

ADS131A02IPBS	ADS131A02IPBSR	ADS131A04IPBS	ADS131A04IPBSR

Qualification Report

ADS131A02IPBS and ADS131A04IPBS offload from DMOS5 to RFAB

Approve Date 11-Dec-2017

Product Attributes

Attributes	Qual Device: ADS131A02IPBS	Qual Device: ADS131A04IPBS	QBS Process Reference: TMP468AIYFF	QBS Package Reference: ADS131A04IPBS
Assembly Site	TAI	TAI	CLARK	TAI
Package Family	TQFP	TQFP	DSBGA	TQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB	RFAB	DM5
Wafer Process	LBC8LV	LBC8LV	LBC8LV	LBC8LV

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL2-260C: ADS131A02IPBS, ADS131A04IPBS

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS131A02IPBS	Qual Device: ADS131A04IPBS	QBS Process Reference: TMP468AIYFF	QBS Package Reference: ADS131A04IPBS
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/2400/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/227/0	3/231/0
HBM	ESD - HBM	2500 V	-	1/3/0	2/6/0	-
CDM	ESD - CDM	1000 V	-	1/3/0	3/9/0	1/3/0
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0	-
LU	Latch-up	(per JESD78)	-	1/6/0	1/6/0	1/12/0
PD	Physical Dimensions	--	-	-	3/60/0	-
SD	Surface Mount Solderability	Pb Free	-	-	3/108/0	-
SBS	WCSP Solder Ball Shear	--	-	-	3/150/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	3/230/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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